

PCN Number:	20161206001	PCN Date:	Dec. 9, 2016
Title:	Datasheet for MSP430F2619S-HT		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details.



MSP430F2619S-HT

SLAS697E – MARCH 2010 – REVISED NOVEMBER 2016

Changes from Revision D (October 2013) to Revision E

Page

- Added *Specifications* section, *ESD Ratings* table, *Thermal Information* table, *Detailed Description* section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section [2](#)
- Changed ORDERING INFORMATION table to *Device Information* table..... [2](#)
- Added 64-pin KGD device [13](#)
- Added new bond pad coordinates table for 80-pin KGD device [13](#)

The datasheet number will be changing.

Device Family	Change From:	Change To:
MSP430F2619S-HT	SLAS697D	SLAS697E

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/MSP430F2619S-HT>

Reason for Change:

To accurately reflect device thermal characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.

Changes to product identification resulting from this PCN:

None.

Product Affected:

MSP430F2619SKGD1	MSP430F2619SPM
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For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com